PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kai-Yu Chu	09/14/2013
Shao-Huai Tsai	09/14/2013
Yu-Han Tsai	09/14/2013
Yi-Hsieh Chiou	09/14/2013

RECEIVING PARTY DATA

Name:	Wistron Corporation
Street Address:	21F., No.88, Sec. 1, Hsintai 5th Rd., Hsichih
City:	New Taipei City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14028546

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	WISP1033USA
NAME OF SUBMITTER:	KATE YEH
Signature:	/KATE YEH/
Date:	09/17/2013

502497446 REEL: 031216 FRAME: 0666

Total Attachments: 8	
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Title of Invention:

PORTABLE ELECTRONIC MODULE AND HEAT DISSIPATING MECHANISM THEREOF

As the below named inventor, I hereby declare that: This declaration is directed to:		
☑ The attached application, or		
☐ United States application number	filed on	, or
☐ PCT international application number	filed on	
The above-identified application was made or authorized to be ma	ade by me.	
I believe that I am the original inventor or an original joint inventor application.	of a claimed invention in the	3
I hereby acknowledge that any willful false statement made in this under18 U.S.C. 1001 by fine or imprisonment of not more than five	declaration is punishable e (5) years, or both.	
In consideration of the payment by Wistron Corporation	having a posta	I address of
21F., No.88, Sec. 1, Hsintai 5th Rd., Hsichih, New Taip	pei City 22181, Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ acknowledged, andfor other good and valuable consideration.	3 1.00), the receipt of which	is hereby
I hereby sell, assign and transfer to ASSIGNEE and the successo the entire right, title and interest in and to any and all improvemen invention as above-identified application and, in and to, all Letters invention by the above application or any continuations, continuations substitutes, or extensions thereof, and as to Letters Patent any rei	ts which are disclosed in the Patent to be obtained for sa ion-in-part, divisions, renewa	e aid als
I hereby covenant that no assignment, sale, agreement or encumbentered into which would conflict with this assignment;	orance has been or will be n	nade or
I further covenant that ASSIGNEE will, upon its request, be provided and documents relating to said invention and said Letters Patent and known and accessible to I and will testify as to the same in any intrelated thereto and will promptly execute and deliver to ASSIGNE	and legal equivalents as may erference, litigation proceed	v be
representatives any and all papers, instruments or affidavits requirmaintain, issue and enforce said application, said invention and sa equivalents thereof which may be necessary or desirable to carry IN WINTNESS WHEREOF, I have hereunto set hand and seal this	aid Letters Patent and said out the proposes thereof.	ate of signing)
Note: An application data sheet (PTO/SB/14 or equivalent), includ inventive entity, must accompany this form. Use this form for <u>each</u>	ing naming the entire additional inventor.	

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NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Kai-Yu Chu

Date:

SEP 1 4 2013

Signature:

kai-Yu chu

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F#NPO-P0002E-US1201 DSC0-102U006518

NPO#WIS-P1033-USA;0 CUST#PWHQ-CA-0904-USXX

Title of Invention:

PORTABLE ELECTRONIC MODULE AND HEAT DISSIPATING MECHANISM THEREOF

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or	r *		
☐ United States application nu	umber	filed on	, or
☐ PCT international applicatio	n number	filed on	
The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original invent application.	tor or an original joint inventor of	a claimed invention in t	the
l hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this de risonment of not more than five (eclaration is punishable 5) years, or both.	1 (1) 19 10 11
In consideration of the payment by	Wistron Corporation	having a pos	tal address of
21F., No.88, Sec. 1, Hsintai 5t	h Rd., Hsichih, New Taipēi	City 22181, Taiwar	n, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the receipt of whic	h is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements wation and, in and to, all Letters Par r any continuations, continuations	which are disclosed in t atent to be obtained for -in-part, divisions, rene	he said wals.
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbra h this assignment;	nce has been or will be	made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interf	l legal equivalents as m erence, litigation proces	av be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said ecessary or desirable to carry out	Letters Patent and said t the proposes thereof.	l Date of signing)
Note: An application data sheet (PT0 inventive entity, must accompany thi	D/SB/14 or equivalent), including s form. Use this form for <u>each ac</u>	naming the entire	

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NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

Inventor: Shao-Huai Tsai Date: SEP 1 4 2013

Signature: Shao thai Tsai

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NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

Title of Invention:

PORTABLE ELECTRONIC MODULE AND HEAT DISSIPATING MECHANISM THEREOF

As the below named inventor, I hereby declare that: This declaration is directed to:		
☑ The attached application, or		
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The above-identified application was made or authorize	d to be made by me.	
I believe that I am the original inventor or an original joir application.	nt inventor of a claimed invention in	n the
I hereby acknowledge that any willful false statement ma under18 U.S.C. 1001 by fine or imprisonment of not mo	ade in this declaration is punishable re than five (5) years, or both.	le ;
In consideration of the payment by Wistron Corpor	ration having a po	ostal address of
21F., No.88, Sec. 1, Hsintai 5th Rd., Hsichih, N	New Taipei City 22181, Taiwa	an, R.O.C.
(referred to as "ASSIGNEE"below) to I of the sum of On acknowledged, andfor other good and valuable consider	e Dollar (\$ 1.00), the receipt of wh ration.	ich is hereby
I hereby sell, assign and transfer to ASSIGNEE and the the entire right, title and interest in and to any and all improvention as above-identified application and, in and to, invention by the above application or any continuations, substitutes, or extensions thereof, and as to Letters Pate	provements which are disclosed in all Letters Patent to be obtained fo continuation-in-part, divisions, ren	the r said ewals.
I hereby covenant that no assignment, sale, agreement entered into which would conflict with this assignment;	or encumbrance has been or will b	e made or
I further covenant that ASSIGNEE will, upon its request, and documents relating to said invention and said Letter known and accessible to I and will testify as to the same related thereto and will promptly execute and deliver to a	s Patent and legal equivalents as in any interference, litigation proc	mav be
representatives any and all papers, instruments or affida maintain, issue and enforce said application, said invent equivalents thereof which may be necessary or desirable IN WINTNESS WHEREOF, I have hereunto set hand ar	ion and said Letters Patent and sa e to carry out the proposes thereof	nid f. (Date of signing)
Note: An application data sheet (PTO/SB/14 or equivale inventive entity, must accompany this form. Use this form	nt), including naming the entire n for <u>each additional inventor.</u>	

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NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

hventor: Yu-Han Tsai Date: SEP 1 4 2013

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NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

F#NPO-P0002E-US1201 DSC0-102U006518

Title of Invention:

PORTABLE ELECTRONIC MODULE AND HEAT DISSIPATING MECHANISM THEREOF

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or	r		
☐ United States application no	umber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	s made or authorized to be made l	by me.	
I believe that I am the original invent application.	tor or an original joint inventor of a	claimed invention in	the
l hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this decrisonment of not more than five (5)	laration is punishabl years, or both.	e
In consideration of the payment by	Wistron Corporation	having a po	stal address of
21F., No.88, Sec. 1, Hsintai 5t	h Rd., Hsichih, New Taipei (City 22181, Taiwa	n, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	0), the receipt of whi	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements wi tion and, in and to, all Letters Pate r any continuations, continuation-i	hich are disclosed in ent to be obtained fo n-part, divisions, ren	the r said ewals
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrand h this assignment;	ce has been or will b	e made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and lestify as to the same in any interfer	egal equivalents as r rence, litigation proc	mav be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne N WINTNESS WHEREOF, I have h	olication, said invention and said L ecessary or desirable to carry out t	etters Patent and sa	id : (Date of signing)
Note: An application data sheet (PT0 nventive entity, must accompany thi	D/SB/14 or equivalent), including r s form. Use this form for <u>each add</u>	naming the entire litional inventor.	

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NPO#WIS-P1033-USA:0 CUST#PWIIQ-CA-0904-USXX

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yi-Hsieh Chiou

Date:

SEP 1 4 2013.

Signature: Yi-Hsieh Chiou

NPO#WIS-P1033-USA:0 CUST#PWHQ-CA-0904-USXX

RECORDED: 09/17/2013

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F#NPO-P0002E-US1201 DSC0-102U006518